

SINGLE-PHASE GLASS PASSIVATED SILICON BRIDGE RECTIFIER

FEATURES

- Glass passivated chip junction
- Low forward voltage drop
- High surge overload rating of 50 Amperes peak
- Ideal for printed circuit board
- High temperature soldering guaranteed:
260°C for 10 seconds

MECHANICAL DATA

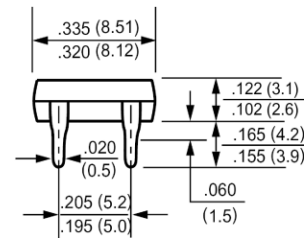
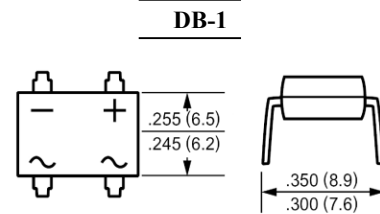
Case: Molded plastic, DB

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202,
method 208 guaranteed

Mounting position: Any

Weight: 0.02ounce, 0.4gram



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	DB201	DB202	DB203	DB204	DB205	DB206	DB207	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current at $T_A=40^\circ\text{C}$	$I_{(AV)}$	2.0							Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	60							Amp
Maximum Forward Voltage at 1.0A DC and 25°C	V_F	1.1							Volts
Maximum Reverse Current at $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage $T_A=125^\circ\text{C}$	I_R	5.0 500							μAmp
Typical Junction Capacitance (Note 1)	C_J	25							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	40							°C/W
Typical Thermal Resistance (Note 2)	$R_{\theta JL}$	15							°C/W
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150							°C

NOTES:

1- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.

2- Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.5 x 0.5" (13 x 13mm) copper pads